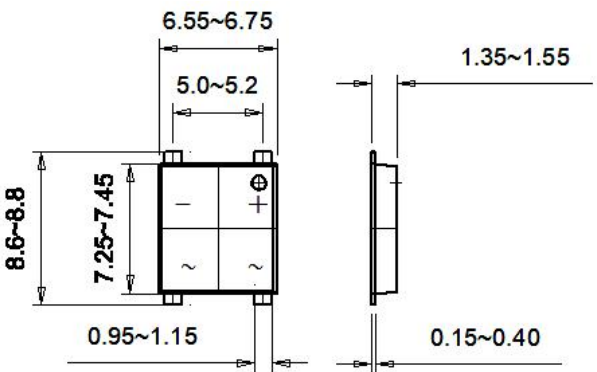




RMSB30A thru RMSB30M

3A Glass Passivated Single-Phase Bridge Rectifier

特征/Features	外形尺寸/Outline Dimensions
◆ GPP芯片 Glass passivated chip ◆ 低反向漏电流 Low Reverse Leakage Current ◆ 高耐浪涌电流能力 High surge current capability ◆ 接线端与壳体间绝缘耐压2500V Case to Terminal Isolation Voltage 2500V	Case: MSB Series Dimensions in millimeters  产品尺寸控制范围: $\pm 0.2\text{mm}$ ROHS COMPLIANT Pb-Free
机械参数/Mechanical Data	
◆ 本体: 塑封 Case: plastic package ◆ 标识/极性: 本体标记 Marking / Polarity: Marked on Body ◆ 重量: 约克 Weight: About 0.24grams	

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted

符号 Symbol	特性 Characteristic	RMSB3							单位 Unit
		0A	0B	0D	0G	0J	0K	0M	
VRRM	最大反向重复峰值电压 Maxmum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
IF (AV)	平均整流输出电流 Average Forward Output Rectified Current@Ta =120℃	3							A
VF	正向峰值电压 Forward Voltage Per Leg @IFM =3.0A	1.2							V
IFSM	正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load	70							A
IR	反向漏电流 Maximum DC reverse current at rated Ta = 25℃ DC blocking voltage per leg Ta = 125℃	5 500							uA
TRR	Maximum reverse recovery time (NOTE 1) 恢复时间	150		250			500		NS
i²t	热容值 Rating for fusing (t<8.3ms)	20.3							A²S
Visol	绝缘耐压 Rms isolation voltage from case to leads	2500							V
CJ	典型结电容 Typical Junction Capacitance	23							pF
RθJC	热阻 Maximum thermal resistance per leg	10							℃/W
Tj, TSTG	结温, 存储条件 Operating Junction and storage temperature range	-55～150							℃

Note:

- (1) Junction to case with heatsink
- (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .



RMSB30A thru RMSB30M

3A Glass Passivated Single-Phase Bridge Rectifier

◆ 特性曲线（典型） Characteristics(Typical)

Fig 1-forwardCurrent derating Curve
图1正向电流降额曲线

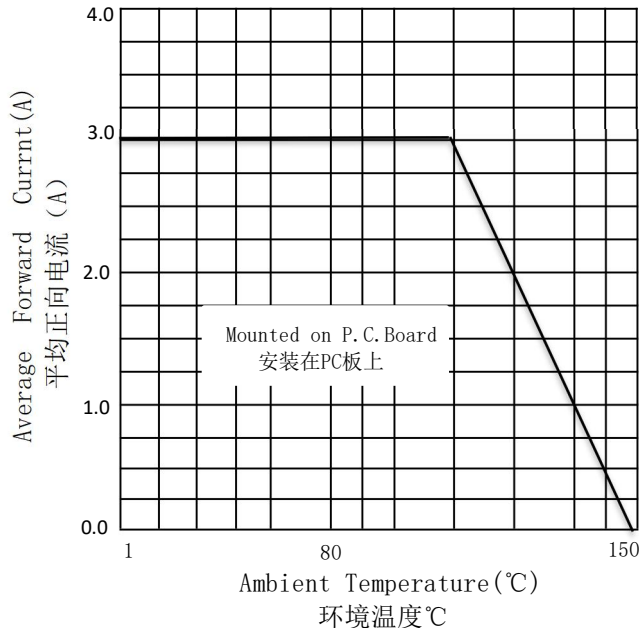


Fig.2-Maximum Non-Repetitive Surge Current
图2 最大不重复正向浪涌曲线

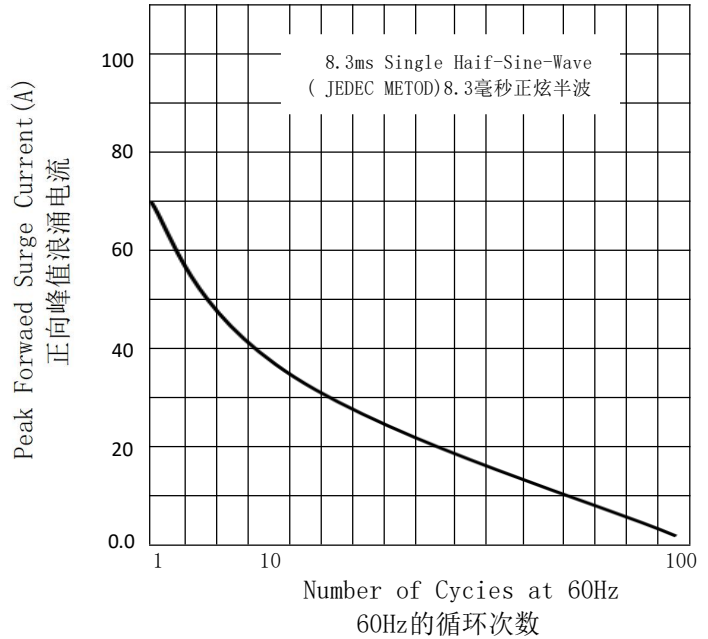


Fig.3-Typical Reverse Characteristics
图3. 典型的反向特性

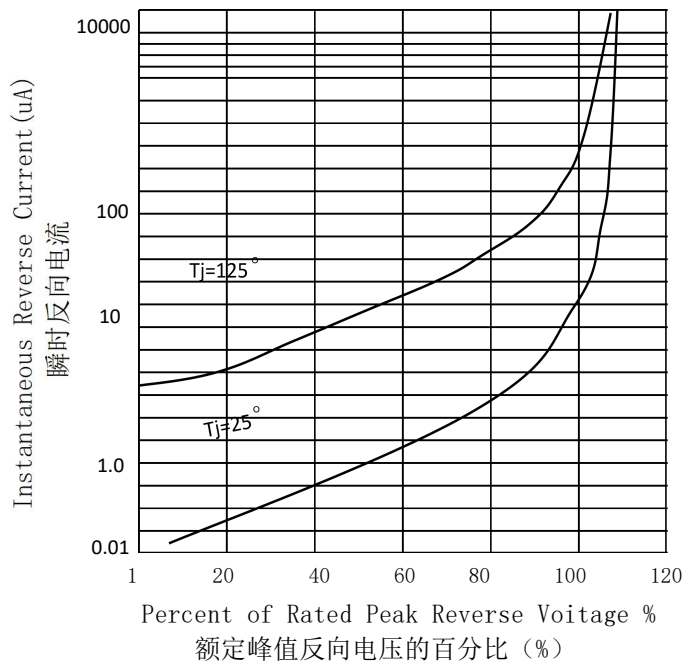
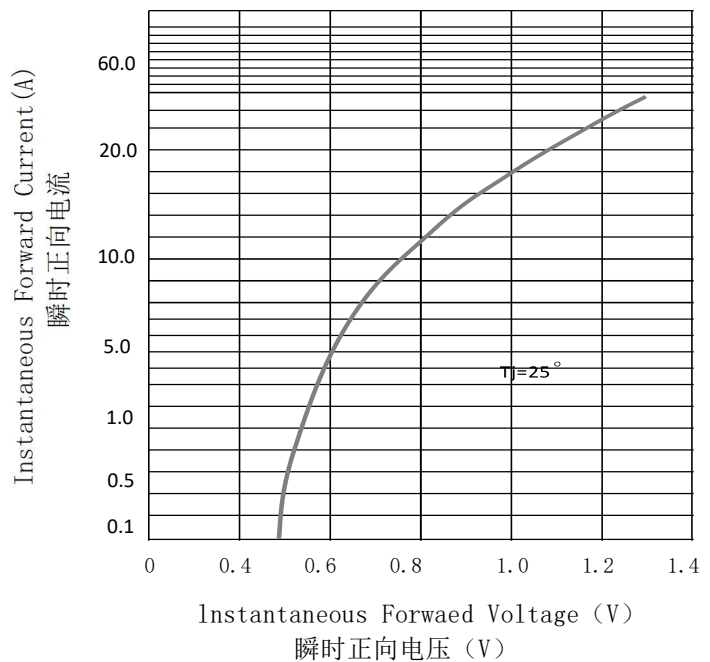


Fig.4-Typical Forward Characteristics
图4. 典型的正向特性

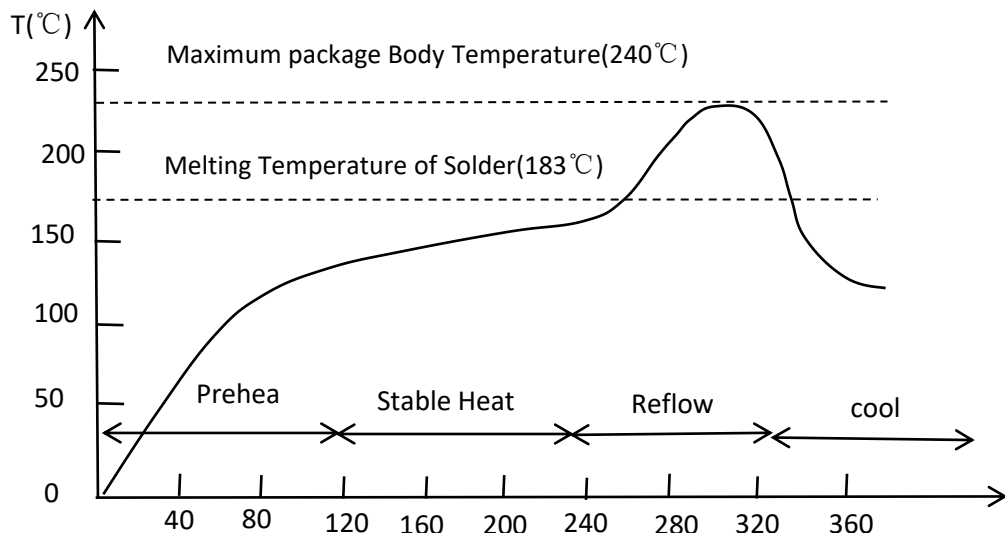




RMSB30A thru RMSB30M

3A Glass Passivated Single-Phase Bridge Rectifier

◆ 焊接温度 (Suggested Soldering Temperature profile



◆ 回流焊方法：红外线、气相炉、热风炉、波峰焊

Recommended reflow methods: IR , vapor phase oven , hot air oven , wave solder .

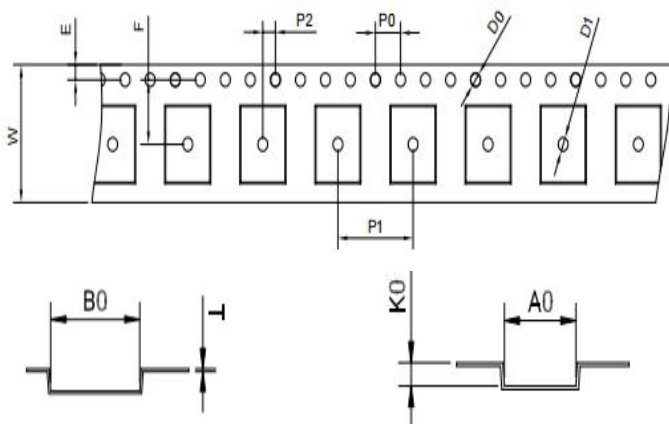
◆ 该装置可在 265° C 的最高温度下暴露 10 秒钟

The device can be exposed to a maximum temperature of 265 ° C for 10 seconds .

◆ 如果回流温度超过建议的温度，则设备可能不符合性能要求。

If reflow temperatures exceed the recommended profile , devices may not meet the performance requirements .

◆ 载带尺寸 Carrier Dimension(mm)



W	AO	BO	KO	E	F
16	7.05	8.8	1.65	1.75	7.50
D0	D1	P0	P1	P2	T
1.6	1.5	4.0	12.0	2.0	0.25

◆ 包装规格 Package Specifications

Package	Reel Siz	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
RMSB	13'	330	3	345	6	440*360*360	54